CHARACTERISTICS CHARACLERISTICS

Panel Dimension: TBD
Board Dimension: 30.00 x 50.95 mm
Material: FR4 150 TG
PCB Thickness: 1.00 mm
Layers: 4
Copper Thickness: Outer 35µ / Inner 35µ
Gap Min / Track Min: 150µ / 150µ
Copper Finish: Chemical Ni/Au
Silkscreen: Top & Bot (White)
Solder Mask: Top & Bot (Green)
Electrical Test: Yes
Controled Impedance: Yes (cf Stack-up below)
UL Marking: Yes IMPERANCE (IC/00 / E- / 7)

IMPEDANCE (IS400 / Er : 4.3)	
TOP-IL1 / Single Ended : 50Ω/ W : 210μ (Microstrip)	KIM1 Ante
TOP-IL1 / Zdiff: 90Ω / W: 180μ / S: 190μ (Edge Coupled External)	USB
IL2_BOT / Zdiff: 90Ω / W: 180μ / S: 190μ (Edge Coupled External)	USB
(3	

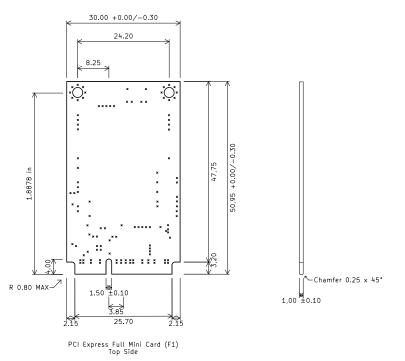
KIM1	Antenna
USB	

PCB STACK-UP	
ТОР	
TSS-00008-X01.gbr / Top SilkScreen	
TSM-00008-X01.gbr / Top Solder Mask	
TOP-00008-X01.gbr / Top Layer / Copper 35μ	Signal
Isolation 0.12 mm - FR4	
IL1-00008-X01.gbr / Int. Layer 1 / Copper 35μ	Plane (GND)
Isolation 0.71 mm — FR4	
IL2-00008-X01.gbr / Int. Layer 2 / Copper 35μ	Plane (+3V3
Isolation 0.12 mm — FR4	
BOT-00008-X01.gbr / Bottom Layer / Copper 35μ	Signal

BSM-00008-X01.gbr / Bottom Solder Mask

воттом

Without Bottom SilkScreen



DRILL MAP									
ALL UNITS ARE IN MILLIMETERS (Finished Holes Size)									
FIGURE	SIZE	TOLERANCE	PLATED	QTY					
×	0.35		Y	122					
0	2.65		Υ	2					

Total Plated Holes Count : 124 Total Unplated Holes Count : 0

	All	dimens	ions	are	in	mil	im	eter, un	ess	othe	rwise	spec	ified.	
W	dime	ensions	tole	ranc	es	are	±	0.15mm	, un	less	other	wise	specified	d.

AI PWAN	
ALPWAN	_

	Product : PCI Express Full Mini Card (F1) / KIM1	Rev : X01	
	Sheet name : Mechanical & Drill Drawing	Date: 2020-06-19	
	File name : BRD-00008-X01.kicad_pcb	Drawn by : SD	D
i	Doc. number : MDD-00008-X01	Size : A4	
	www.alpwan.fr / support@alpwan.fr	Sheet : 1/1	

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